

STG ELECTRONIC CO.,LTD

PCB capacity:

Rigid pcb production capacity:

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|---------------------------|--|
| Material Thickness | 0.35mm-6.4mm |
| Copper Thickness | Up to 6 oz Cu |
| Max board size | 610 mm x 711mm(24' x 28') |
| Standard Surface finish | Hot Air Solder Level |
| Alternative finishes | Electroless Nickel / Immersion Gold |
| | Silver |
| | Electroless Tin Lead |
| | Organic (OSP) |
| | Hard Gold (edge contact) |
| | Carbon |
| | Peelable |
| Bare Board Test | Bed of Nails |
| | Simultaneous double-sided flying probe test |
| Solder mask | Photoimageable Resist with a wide range of colours. |
| Gold plate | Edge connectors Touch Pads |
| Min. via size and type | Dia.0.15mm(finished) Aspect Ratio=12; HDI holes(<0.10mm) |
| Min.Line width&spacing | 0.10 mm/0.10mm(4mil./4mil) |
| Min.via hole size and pad | via:dia.0.2mm/ pad:dia.0.4mm;HDI<0.10mm via |
| | |

Flexible pcb production capacity:

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|-----------------------------------|--|
| Material | Polyimide (Kapton),Polyester(PET) |
| Number of Layer | 1-4layers,1-2layers |
| Min.trace width/space single side | 0.075mm(3 mil) for single-sided board |
| | 0.08mm (4mil) for double-sided board |
| Solder Resist | Laminating of cover film,Liquid sensitization solder mask printing ink |

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| Surface Treatment | Spray stnnum tin and sunk stannum, Nickelplated gold,Chemistry turneric, Oxidation protection (OSP) |
| Weldability | 245+/-5 degree. 3-5s |
| Winding,Bending,Endurance | >100,000times |
| Thermal Stress Test | 288+/-5 degree, 10s once |
| Rosh,E-testing | Yes |

Aluminum pcb production capacity:

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|-----------------------|--|
| Product Type | Al Clad PCB 1 layer |
| Copper thickness | 0.5oz, 1oz, 2oz, 3oz and 4 oz |
| Board Thickness | 0.4mm To 4.0mm |
| Aluminum Machining | Drilling,Tapping,Milling,Routing, Die-Punching,break-off tab available |
| Min. Finish hole size | 0.25mm |
| Min.Track Width | 0.2mm (8mils) |
| Surface Finishing | HASL, HASL Leadfree, Immersion gold, Flash gold, OSP |
| Reference Standard | IPC-A-600G Class 2 |
| Special holes | Spot facing, Cup holes |
| Rosh and E-testing | yes |

PCBA Capability

| | | | |
|------------------------|----|----------------------------------|---------|
| | 1 | RoHS Assembly | Y |
| | 2 | Double Sided Assembly | Y |
| | 3 | SMT Assembly | Y |
| | 4 | Manual Soldering | Y |
| | 5 | Min Passive Component Size | 0201 |
| | 6 | Min BGA Pitch | 0.4mm |
| | 7 | Number of Assembly lines | 6 |
| | 8 | IPC-A-610 | Class 2 |
| | 9 | X-Ray Inspection | Y |
| | 10 | Electronic/ Bed of Nails Testing | Y |
| | | | |
| Final Product Assembly | | | |
| | 1 | Box Build | Y |
| | 2 | ABS Plastic Injection Molding | Y |
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